

Application Circuit of Low Noise Op-Amp TC75S67TU for Current Sensor

Reference Guide

RD161-RGUIDE-01

Overview

This reference guide describes the specifications, board patterns, usage, and characteristics of the current sensor (hereinafter referred to as the "sensor") using the low-noise operational amplifier TC75S67TU. A microcontroller can be used to control operations and display results. Please refer to this section when designing a current sensor using a TC75S67TU.

TOSHIBA ELECTRONIC DEVICES & STORAGE CORPORATION

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1. Introduction

The current sensor described in this reference guide uses a simple-structured shunt resistor as the current sensing method. In addition to being able to measure currents up to 2 A, we also designed a GND sense and a ringing detection for current. It can be widely used for a variety of applications, current sensing for battery-powered devices such as notebook PCs and electronic cigarettes, and overcurrent protection for home appliances. Arduino is used for the microcontroller to control operations and to display the results on the computer. The power supply also uses a 5 V DC voltage supplied by Arduino, so it can be used as a current sensor if there is a Arduino and a personal computer in addition to this sensor.

To download of the various offer information on this sensor reference design →

[Click Here](#)

The components other than the op-amp are also mounted on a compact board size of 20 mm x 20 mm using surface mount, making it easy to use for a variety of applications.

2. Specifications and Appearance

2.1. Specification

Table 2.1 Current Sensor Circuit Specifications

Item	Specification
I/F	Arduino connectivity
Control method	Control from Arduino and Shield connected PCs
Power supply voltage	Arduino and Shield board feed 5 V
Measured current	Maximum 2 A
Shunt resistor	RL73H3AR10FTE of TE connectivity 100 mΩ, ±1 % accuracy, 1 W@70 °C
On-board operational amplifier	Toshiba Device & Storage TC75S67TU

2.2. Appearance

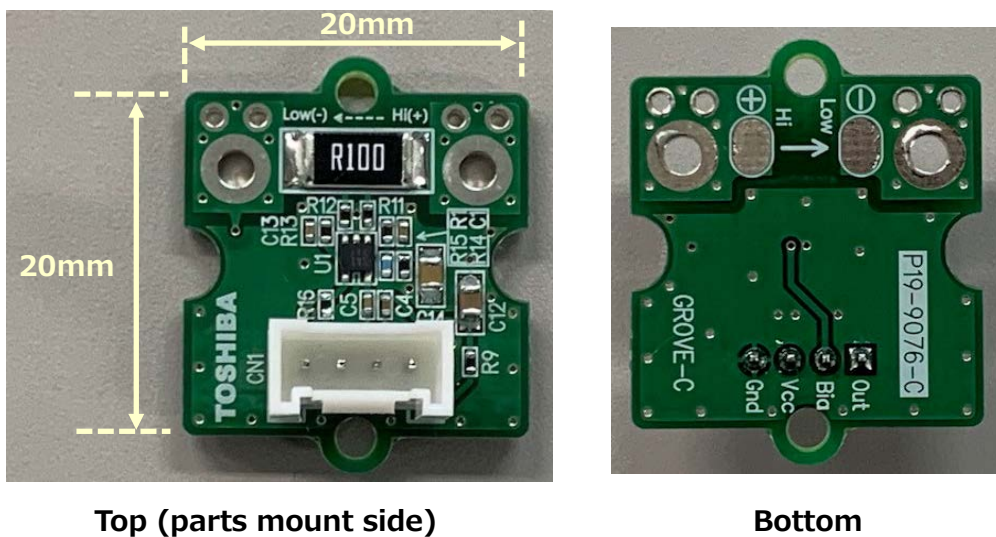


Fig. 2.1 Current Sensor Appearance

3. Circuit and Board Pattern

3.1. Circuit Diagram

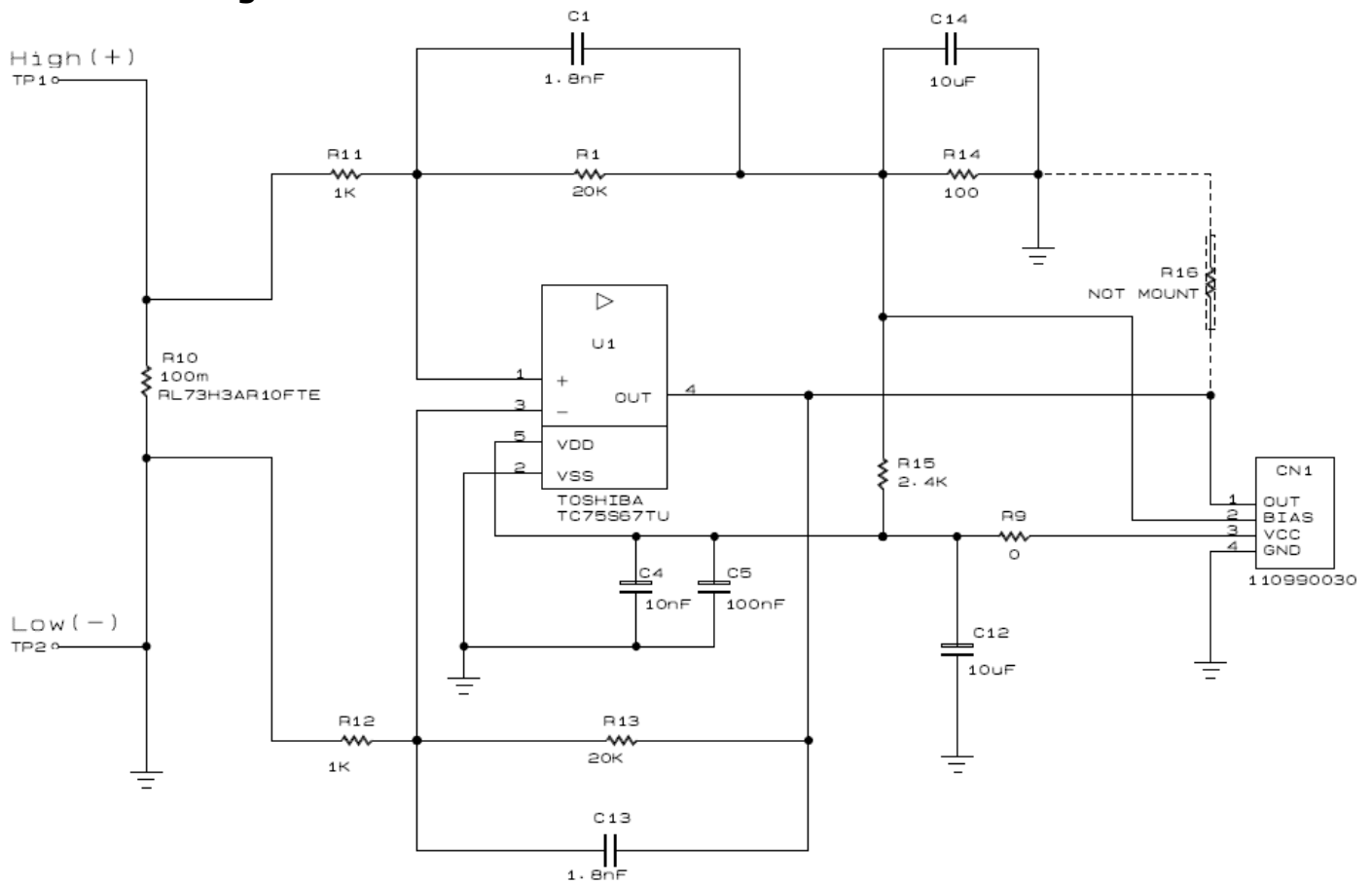


Fig. 3.1 Current Sensor Circuit Diagram

3.2. Bill of Materials

Table 3.1 Bill of Materials

Item	Parts	Q'ty	Value	Part name	Manufacturer	Description	Package Name	Standard dimensions mm (inch)	Mounting
1	U1	1	-	TC75S67TU	TOSHIBA	Operational amplifier	SOT-353F	2.0×2.1×0.7	
2	C1, C13	2	1800 pF			Ceramic 50 V, ±10 %		1.0×0.5 (0402)	
3	C4	1	10 nF			Ceramic 25 V, ±10 %		1.0×0.5 (0402)	
4	C5	1	100 nF			Ceramic 16 V, ±10 %		1.0×0.5 (0402)	
5	C12, C14	2	10 μF			Ceramic 25 V, ±10 %		2.0×1.2 (0805)	
6	R1, R13	2	20 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
7	R9	1	0 Ω			1 A		1.0×0.5 (0402)	
8	R10	1	100 mΩ	RL73H3A R10FTE	TE connectivity	Shunt resistor 1 W, ±1 %		6.4×3.2 (2512)	
9	R11, R12	2	1 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
10	R14	1	100 Ω			100 mW, ±1 %		1.0×0.5 (0402)	
11	R15	1	2.4 kΩ			100 mW, ±1 %		1.0×0.5 (0402)	
12	R16	1						1.0×0.5 (0402)	Not mounted Dummy load
13	CN2	1	-	110990030	Seed Studio	Grove connector 4 pins/straight		10×5.1×8.1	

3.3. Board Pattern Drawing

This board consists of both top and bottom sides. The parts mounting side is top side.

<Top Side (Parts Mounting Side)>

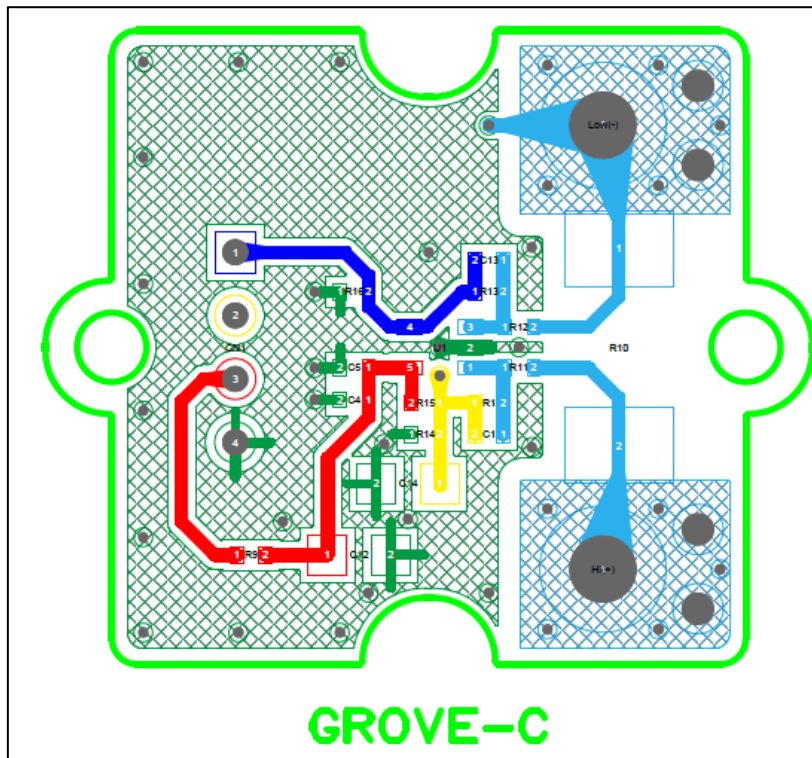


Fig. 3.2 Board Pattern

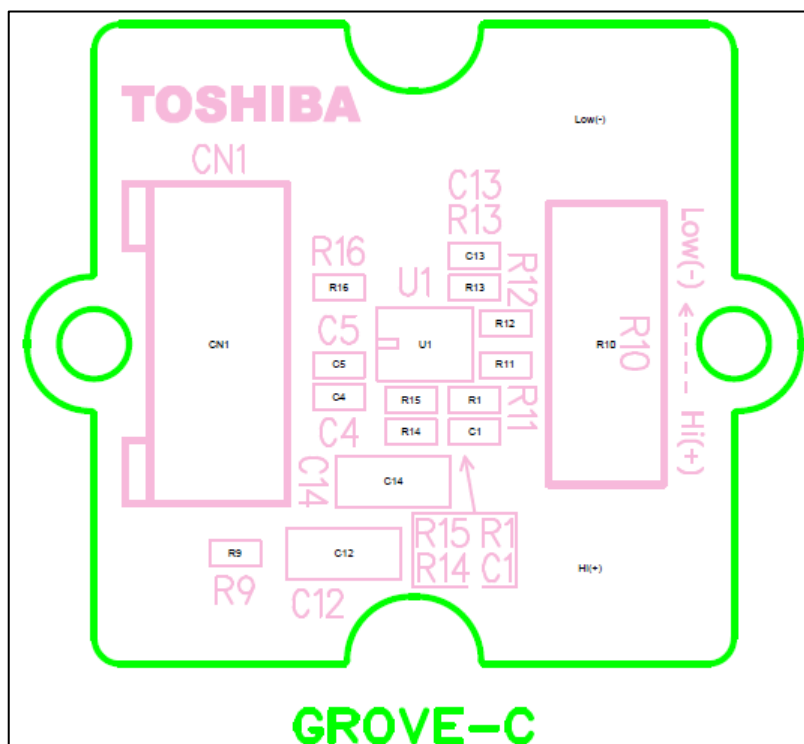


Fig. 3.3 Substrate Silk

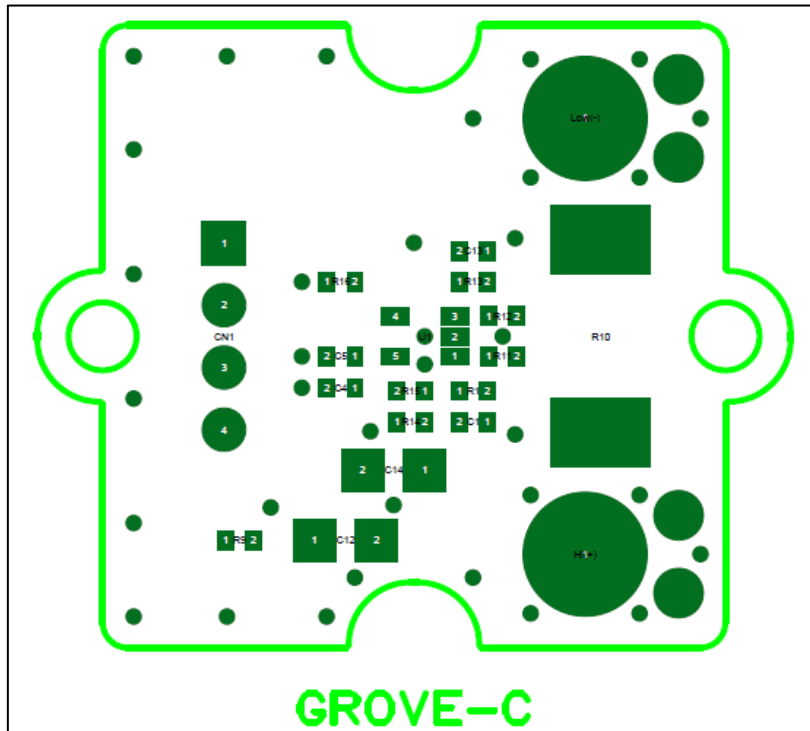


Fig. 3.4 Substrate Solder

<Bottom Side>

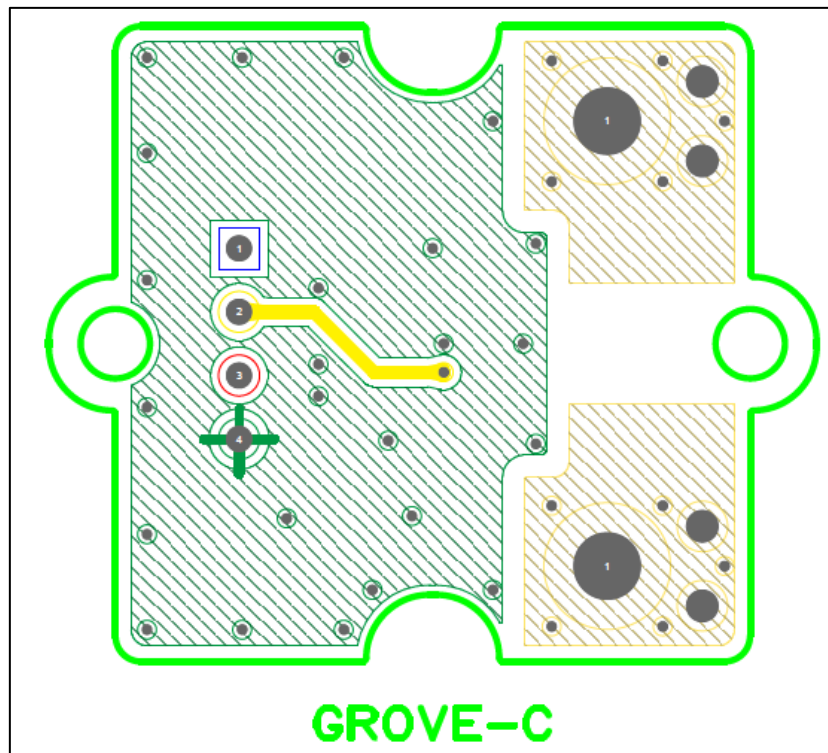


Fig. 3.5 Board Pattern

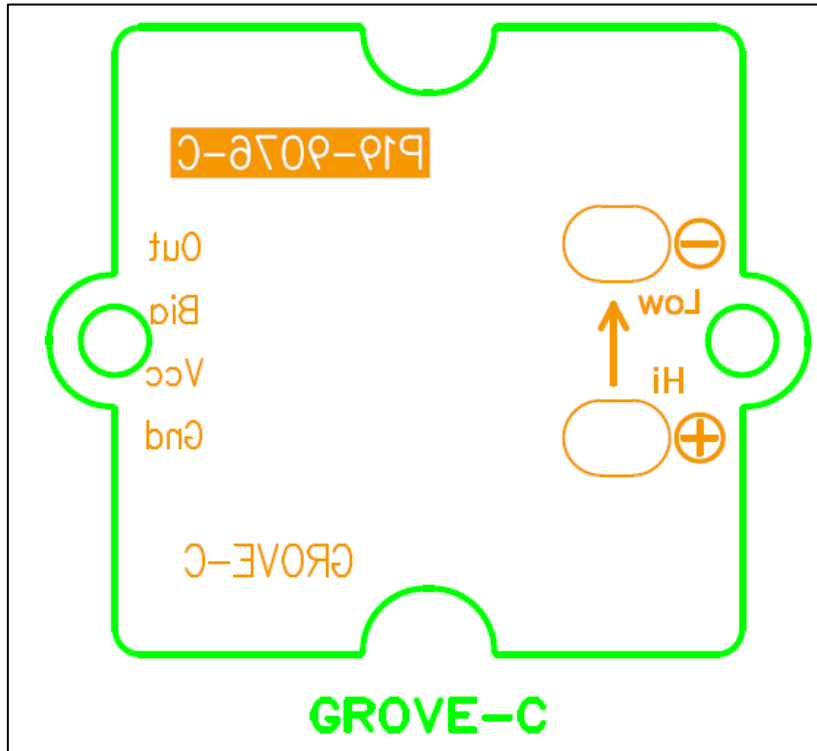


Fig. 3.6 Substrate Silk

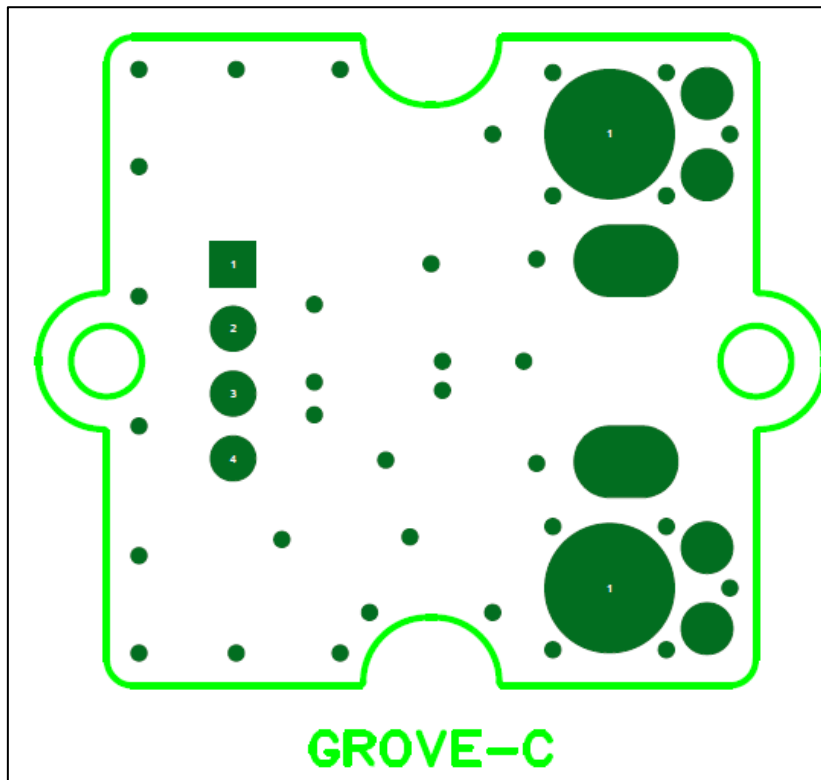


Fig. 3.7. Substrate Solder

4. Operation Procedure

4.1. Arduino and Processing

Arduino is a palm-sized one-board microcontroller. The microcontroller is selected as the control microcontroller for this reference design because it is generally available on the market and can be easily got, and if the program is transferred once, the sensor can be operated without a PC. Use the Processing to display the measurement results on the PC-screen.

This reference design provides Arduino operating program and a Processing program that displays the status of measurements. To run this program, you must install Arduino IDE and Processing 3 on your PCs. Both software are available free of charge on their official sites. Download the software and install it on your PC in advance. These software are also needed to edit each program. These programs are called "sketches" in Arduino, Processing.

Moreover, in the case of Windows10, a display window for result of Processing may not start. In such a case, it is necessary to change the configuration file of initial value that generated automatically at the first time start-up of Processing. Since a solution change with PCs, please implement a suitable solution with reference to Web etc.

Refer to the Commercial Instructions for more information on Arduino and Processing.

4.2. Connecting to Arduino

Fig. 4.1 shows an example of connecting to Arduino.

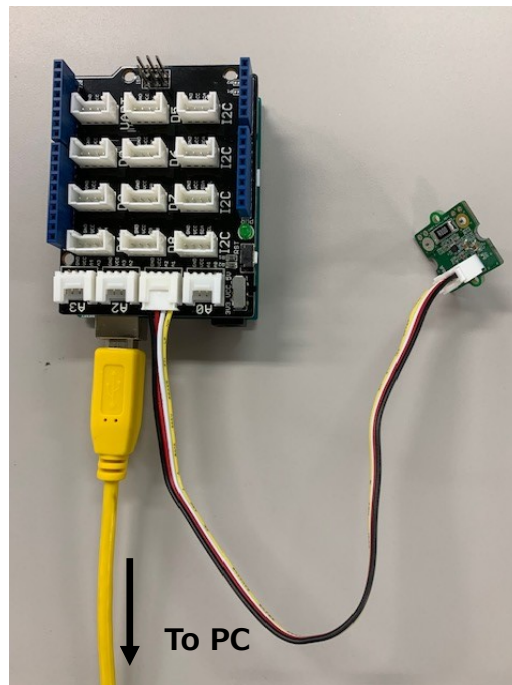


Fig. 4.1 Connection to Arduino

Arduino is used with "seed studio Base Shield". The connection port of the base shield to the sensor is connected A1 terminal. Connect the base shield and the PC with a USB cable.

4.3. Start and Stop

When the compressed file "RD161-SKETCH-01_E.zip" of the sketch prepared for this sensor is downloaded from the following link and decompressed in an appropriate place on the PC, the folder containing the two files "Current_sensor_Arduino.ino" and "Current_sensor.pde" and the usage convention is created. Save the file as is.

To download sketches → [Click Here](#)

Start the Arduino IDE and select "File" → "Open" to open the saved Current_sensor_Arduino.ino file. The window shown on the left of Fig. 4.2 opens separately from the window opened at startup. Select "Sketch" → "Upload" to start compiling the files and write the sketch to the Arduino after compiling. When writing is completed successfully, a message appears at the bottom of the window. The Arduino is now ready.

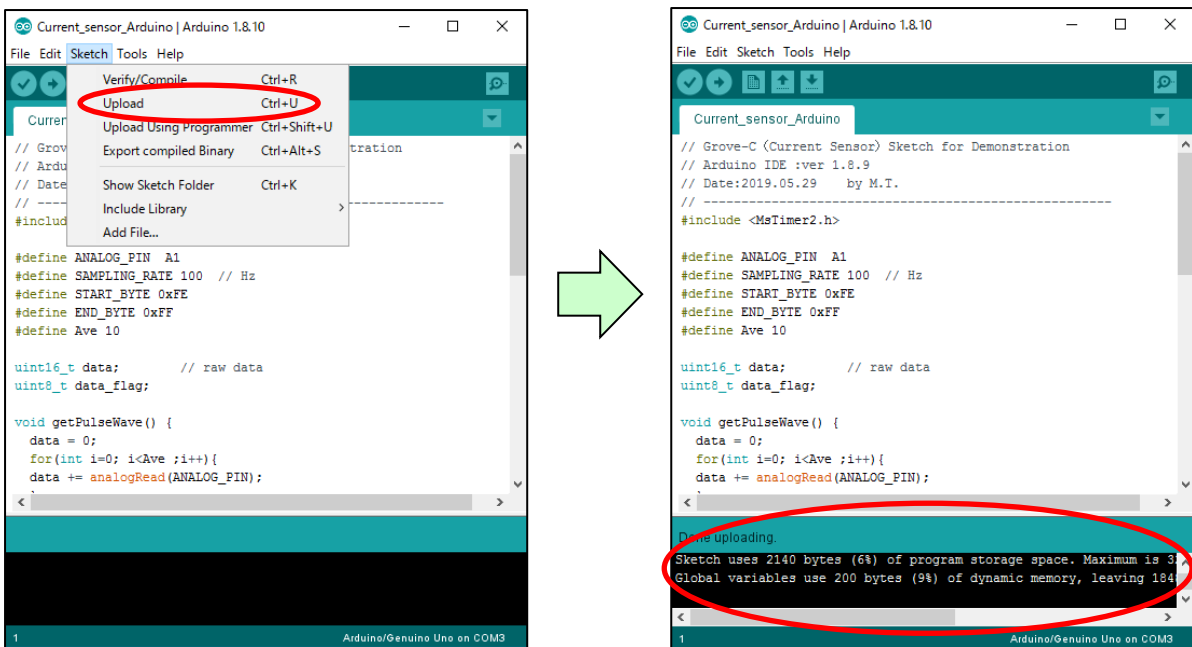


Fig. 4.2 Arduino IDE Window

Then start the Processing 3. When you start the Processing 3, the window shown in Fig. 4.3 opens. Click Get Started at the bottom right of the child window. Then, select File → Open to open the saved Current_sensor.pde file.

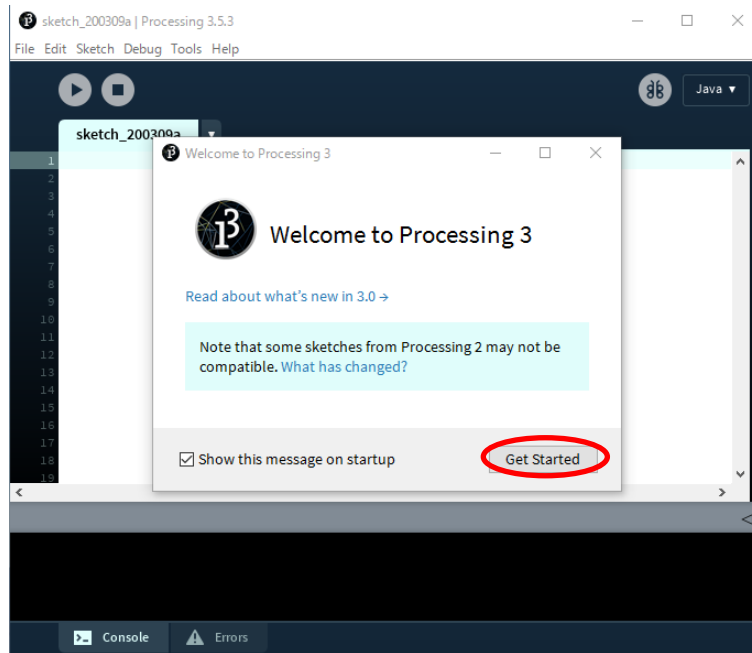


Fig. 4.3 Startup window of Processing 3

The window shown in Fig.4.4 opens separately from the window opened at startup. Click the operation button (red circle) here to open the result display window and start the measurement.

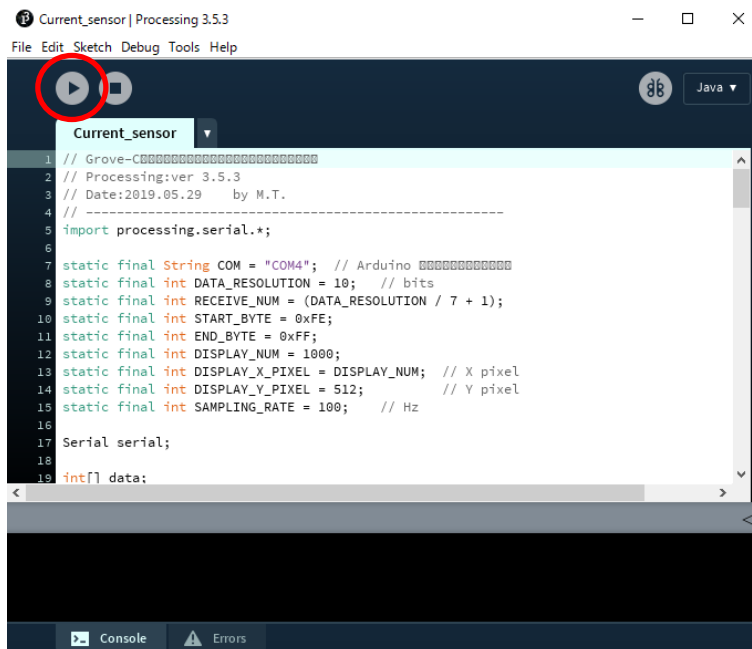


Fig. 4.4 Processing Measurement Start Window


```

60     textSize(28);
61     fill(255, 0, 0);
62     text( "Current : " + nf((float)(value-41)*2500.0/1023.0/1000.0,1,2) + " A", 435, 41);
63 }
64 }
65 //println(frameRate);
66 }

```

Fig. 4.6 Line 62 of Processing Sketch

In the red box shown in Fig. 4.6, the input voltage to Arduino is calculated by counting the LSBs (Least Significant Bit) of the input A/D converter, and "value" is the result of measuring the output voltage of the operational amplifier including the offsets. The bottom-up voltage is subtracted from this point to cancel.

Since Arduino input A/D converter has 10 bits, the voltage V_{LSB} per 1 count of LSB is as follows.

$$V_{LSB} = \frac{V_{CC}}{2^{10}-1} = \frac{5}{1023} \cong 0.00488 = 4.88 \text{ (mV)} \quad \dots (4.1)$$

The denominator in this equation subtracts 1 from 2^{10} , because 0 is the first count.

If the output offset voltage is V_{OS} , the number of offset voltages counted by LSBs (the number subtracted from "value") x is obtained by the following equation 4.2.

$$x = \left\lceil \frac{V_{OS}}{V_{LSB}} - 0.5 \right\rceil = \left\lceil \frac{V_{OS}}{\left(\frac{V_{CC}}{2^{10}-1}\right)} - 0.5 \right\rceil = \left\lceil \frac{V_{OS} \times (2^{10}-1)}{V_{CC}} - 0.5 \right\rceil = \left\lceil \frac{V_{OS} \times 1023}{5} - 0.5 \right\rceil \quad \dots (4.2)$$

Since the count number is an integer value that is closest to V_{OS} divided by V_{LSB} , Equation 4.2 performs an operation (ceiling function) that gives the smallest integer that is greater than or equal to the value obtained by subtracting 0.5 from the result of the division. The symbol " $\lceil \]$ " in the equation indicates the ceiling function.

When there is no offset of the operational amplifier, V_{OS} is 0.2 V. Therefore, the count number at this time is 41 as shown in the equation 4.3 below.

$$x = \left\lceil \frac{0.2 \times 1023}{5} - 0.5 \right\rceil = \lceil 40.92 - 0.5 \rceil = 41 \quad \dots (4.3)$$

Processing sketches provided in this reference design defaults to 41. When there is a zero point shift, please make adjustments according to the following. Sketches can be edited and saved on Processing.

The following explains the procedure by taking the case where zero point misalignment of 0.01 A occurs as an example.

Since the voltage drop of the shunt resistor ($100 \text{ m}\Omega=0.1 \ \Omega$) generated by the current equal to the displayed deviation is considered to be the input-offset voltage V_{IO} of the op-amp, V_{IO} is assumed to be 1 mV as shown in the equation 4.4.

$$V_{IO} = 0.01 \times 0.1 = 0.001 = 1 \text{ (mV)} \quad \dots (4.4)$$

At this time, the output offset voltage V_{OS} of the op-amp is the voltage which added 0.2 V for a bottom raising to the voltage which increased V_{IO} 20 times, and is obtained as shown in the equation 4.5 below.

$$V_{OS} = 0.2 + 0.001 \times 20 = 0.22 \text{ (V)} \quad \dots (4.5)$$

Assign this to the equation 4.2 to calculate the count.

$$x = \left\lfloor \frac{0.22 \times 1023}{5} - 0.5 \right\rfloor = \lfloor 45.012 - 0.5 \rfloor = \lfloor 44.512 \rfloor = 45 \quad \dots (4.6)$$

Change Processing sketch line 62 (Fig 4.6) as follows:

```
text("Current : " + nf((float)(value-45)*2500.0/1023.0/1000.0,1,2) + " A", 435, 41);
```

In Processing sketch of this reference design, the smallest digit of the result display is larger than the resolution determined by the LSB. Therefore, the zero point deviation may not be eliminated. If this happens, adjust the value one by one while viewing the actual result display.

4.5. Precautions for Evaluation

- The resolution of this current sensor is approximately 2.4 mA.
- Although the shunt resistor of the current sensor is set to a minute resistance value in consideration of heat generation, it may become hot if the current continues to flow for a long time. Be careful not to touch the board directly in such a case as this may cause burns.
- The current sensor in this guide is designed to be connected to the low (GND) side of the load with the shunt resistor's Low (-) terminal grounded. It cannot be used by connecting to the high (power supply) side.
- When this current sensor is connected, it may affect the start and stop sequence of the equipment that is the load.

5. Current Measurement Results

In Processing, the current calculated from the measured value is displayed.

A measurement result display window when a DC power supply is connected to shunt resistor and turned on is shown below.

Fig.5.1 shows a waveform when current is set as 0.10 A, Fig.5.2 shows a waveform when it is set as 1.50 A. The displayed current value shows the value after power ON.

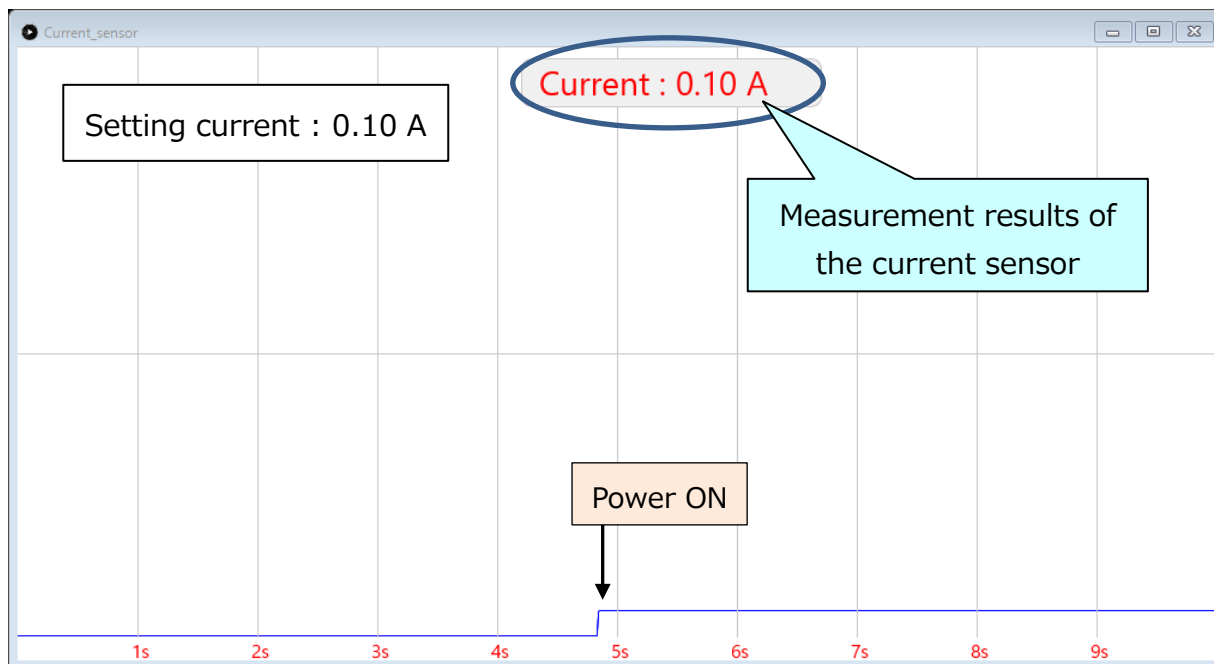


Fig. 5.1 Measurement Result Indication by Processing (1)

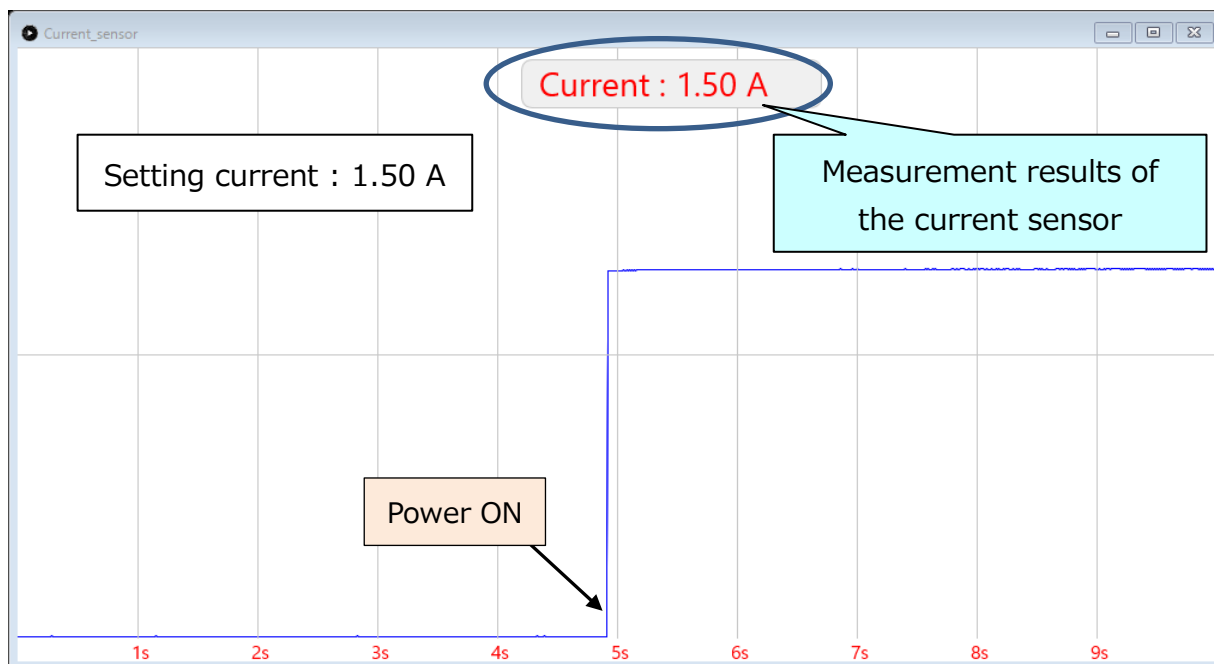


Fig. 5.2 Measurement Result Indication by Processing (2)

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